

BMEP583040

Schneider Electric · Modicon M580

Modicon M580 ePAC CPU, Level 3, Remote I/O (RIO/DIO)

Processor

ARM dual-core

Clock speed

600 MHz

Program memory

12 MB integrated RAM (application program)

Data memory

768 KB data memory

Internal RAM

Integrated (see program/data memory)

Programming software

EcoStruxure Machine Expert (Unity Pro XL)

Scan speed

40 Kinst/ms (100% boolean) / 30 Kinst/ms (mixed)

Performance level

Level 3

Discrete I/O (max)

3072 points

Analog I/O (max)

768 points

Application channels

64

Compatible racks

4, 6, 8, 12 slots (single PSU); 6, 10 slots (redundant PSU) — X80 Ethernet backplane

Local racks

8 racks total (1 main + 7 expansion)

Expansion racks

7 expansion racks

Remote I/O drops

16 remote I/O drops

Distributed devices (DIO)

61 distributed devices

Built-in ports

1× Ethernet service port (RJ45), 2× Ethernet RIO/DIO ports (RJ45, 10/100 Mbps), 1× USB Mini-B (480 Mbps)

Protocols

Modbus TCP/IP, EtherNet/IP, HTTP/HTTPS (Web server), Modbus Serial (via USB or comm module)

Ethernet networks

3 Ethernet networks

Web server

Standard (diagnostic/maintenance)

Communication expansion

X80 backplane communication modules (BMENOC03xx Ethernet/IP, BMENOS0300 serial, BMENOR2200 RIO, BMENUA0100 universal automation)

Supply voltage

24 V DC (19.2-31.2 V DC via backplane)

Power consumption

7.2 W

Bus current

300 mA @ 24 V DC

Operating temperature

0°C to +60°C

Storage temperature

-25°C to +70°C

Relative humidity

5% to 95% (non-condensing)

Protection rating

IP20

Dimensions (H×W×D)

100 × 56 × 93 mm

Weight

0.849 kg

Slot occupation

2 slots (slots 0 and 1)

SD card

4 GB optional (BMXRMS004GPF)

Lifecycle

Active (current flagship ePAC platform, introduced 2014, replaces Quantum/Premium) (Last verified: 2026-09)